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Date _____ Sig: _____
Marjorie Scariati

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

APPLICANT(S): David Mui et al.

SERIAL NO.: 09/905,172

FILING DATE: 07/13/01

TITLE: ETCH PATTERN DEFINITION USING A CVD ORGANIC LAYER AS AN ANTI-REFLECTION COATING AND HARDMASK

ART UNIT: 1765

ATTY DOCKET: 6188 (OLD) / 004227 USA02/ETCH/SILICON/JB1 (NEW)

Box Missing Parts
Assistant Commissioner for Patents
Washington, DC 20231

LETTER REQUESTING CHANGE OF ATTORNEY DOCKET NUMBER

A Response to Notice to File Missing Parts is filed herewith.

The above application was filed on July 13, 2001, identified by attorney docket number 6188. It is respectfully requested that the attorney docket number on this application be changed to 004227 USA02/ETCH/SILICON/JB1. All documents included in the enclosed Response to Notice to File Missing Parts reflect the revised docket number, and it is requested that all future Patent Office communications be identified by the new docket number accordingly.

Respectfully submitted,

Robert W. Mulcahy Reg. No. 25,436

Date: _____

OATH & ASSIGNMENT

1. The undersigned hereby undertake that the invention/new utility model/new design entitled:

Title: ETCH PATTERN DEFINITION USING A CVD ORGANIC LAYER AS AN ANTI-REFLECTION COATING AND HARDMASK

was truly invented by me/us. The undersigned agree to accept punishments provided for in laws in case of any imposture, plagiarism, imitation or deceptive activities

2. The undersigned hereby assign all my/our rights and interests regarding the invention/new utility model/new design, including the right to claim priority, insofar as the Republic of China is concerned to: APPLIED MATERIALS, INC.

a corporation organized and existing under the laws of the State of Delaware, United States of America and located at 3050 Bowers Avenue, Santa Clara, California 95054, U.S.A.

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List of Reference Numbers

130	Material to be etched
140	CVD organic layer
150	Dielectric layer
160	Patterned photoresist layer
210	Silicon substrate
220	Gate oxide layer
230	Doped polycrystalline silicon layer
240	CVD organic layer
250	Silicon oxynitride layer
260	Patterned photoresist layer
310	Semiconductor substrate
320	Pad oxide layer
330	Silicon nitride layer
340	CVD organic layer
350	Silicon oxynitride layer
360	Patterned photoresist layer